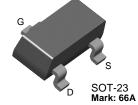


# MMBF5103

### **N-Channel Switch**

- This device is designed for low level analog switching, sample and hold circuits and chopper stabilized amplifiers.
- Sourced from Process 51.
- See J111 for characteristics.



1. Drain 2. Source 3. Gate

# **Absolute Maximum Ratings\*** T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{DG}$	Drain-Gate Voltage	40	V
V <sub>GS</sub>	Gate-Source Voltage	-40	V
I <sub>GF</sub>	Forward Gate Current	50	mA
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	- 55 ~ 150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
  These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

## Electrical Characteristics Ta=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Charact	eristics	·			•
V <sub>(BR)GSS</sub>	Gate-Source Breakdown Voltage	$I_G = 1.0 \mu A, V_{DS} = 0$	-40		V
I <sub>GSS</sub>	Gate Reverse Current	$V_{GS} = -15V, V_{DS} = 0$ $V_{GS} = -15V, V_{DS} = 0, T_a = 125^{\circ}C$		-200 -500	pA nA
V <sub>GS(off)</sub>	Gate-Source Cutoff Voltage	$V_{DS} = 20V, I_{D} = 1.0nA$	-1.2	-2.7	V
V <sub>GS(f)</sub>	Gate-Source Forward Voltage	$I_G = 1.0 \text{mA}, V_{DS} = 0$		1.0	V
On Characte	eristics	·			
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current *	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0	10	40	mA
Small Signa	I Characteristics	·			•
C <sub>ISS</sub>	Input Capacitance	$V_{DS} = 15V, V_{GS} = 0, f = 1.0MHz$		16	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	V <sub>GS</sub> = -15V, f = 1.0MHz		6.0	pF
	e Width ≤ 300μs, Duty Cycle ≤ 1.0%	1		ı	

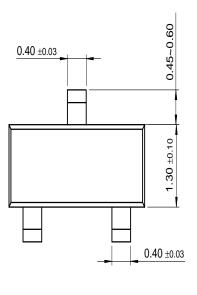
### Thermal Characteristics T<sub>a</sub>=25°C unless otherwise noted

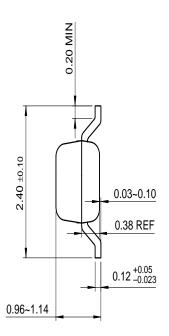
Symbol	Parameter	Max.	Units
P <sub>D</sub>	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	556	°C/W

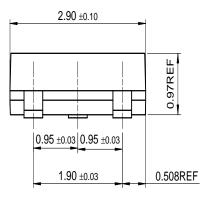
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# **Package Dimensions**

# **SOT-23**







Dimensions in Millimeters

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CoolFET™	FRFET™	MicroPak™	QS™	TinyLogic <sup>®</sup>
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EcoSPARK™	HiSeC™	MSXPro™	RapidConfigure™	UHC™
E <sup>2</sup> CMOS <sup>TM</sup>	I <sup>2</sup> C <sup>TM</sup>	OCX <sup>TM</sup>	RapidConnect™	UltraFET <sup>®</sup>
EnSigna™	ImpliedDisconnect™	OCXPro™	SILENT SWITCHER®	VCX™
FACT™	ISOPLANAR™	OPTOLOGIC <sup>®</sup>	SMART START™	
Across the board.	Around the world.™	OPTOPLANAR™	SPM™	
The Power Franci	hise™	PACMAN™	Stealth™	
Programmable Ad	ctive Droop™	POP™	SuperSOT™-3	

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